

# FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

*Patent fees are subject to annual revisions on or about October 1st of each year.*

Large Entity

**TOTAL FEES AUTHORIZED: \$ 780**

The commissioner is hereby authorized to charge indicated processing and/or publication fees and credit any overpayments to:

Deposit Account Number: 500801



Deposit Account Name: NORTH AMERICA INTERNATIONAL PATENT OFFICE

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

## SUBMITTED BY

Authorized Name: WINSTON HSU  
 Electronic Signature Mark: VAEB-JMXX-8IIL  
 Date Signed: 20021031

## BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	1001	\$ 740

Subtotal For Basic Filing Fee: \$ 740

## EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 10	1202	\$ 18	0	\$ 0
Independent Claims: 3	1201	\$ 84	0	\$ 0

Subtotal For Extra Claims Fees: \$ 0

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40

Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 19372  
Application ID: 10065568  
Title of Invention: SOLDER BUMP STRUCTURE AND  
LASER REPAIR PROCESS FOR  
MEMORY DEVICE  
First Named Inventor: Kuo-Ming Chen  
Domestic/Foreign Application: Domestic Application  
Filing Date: null  
Effective Receipt Date: 2002-10-31  
Submission Type: Utility Patent Filing  
Filing Type: new-utility  
Confirmation Number: 0  
Attorney Docket Number: NAUP0482USA  
Digital Certificate Holder: cn=Winston Hsu, ou=Registered Attorneys, ou=Patent and  
Trademark Office, ou=Department of Commerce; o=U.S.  
Government, c=US  
Certificate Message Digest: zq0+veBWgFxxKnpwjk/UGA==  
Total Fees Authorized: \$780.0  
Payment Category: DA - Deposit Account  
Deposit Account Number: 500801  
Deposit Account Name: WINSTON HSU





# TRANSMITTAL FORM

Electronic Version 1.0.3

Stylesheet Version: 1.0

Attorney Docket  
Number:

NAUP0482USA

Submission Type: Utility  
Patent Filing

## SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR MEMORY DEVICE

First Named Inventor: Kuo-Ming Chen

### SUBMITTED BY

Name:	Mr. Winston Hsu
Registration Number:	41,526
Electronic Signature Mark: Winston Hsu	Date Signed: 20021031
Name:	Mr. Mord Michael Lewis
Registration Number:	50,478
Electronic Signature Mark: Mord Michael Lewis	Date Signed: 20021031

*I certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.*

*I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.*

**Attached Files:**

declaration	NAUP0482DEC1.TIF
declaration	NAUP0482DEC2.TIF
specification	NAUP0482.xml
bibd-transmittal	NAUP0482apds.xml
patent-assignments	NAUP0482asgn.xml
fee-transmittal	NAUP0482fee.xml

**Attached Image File(s):**

NAUP0482DEC1.TIF  
NAUP0482DEC2.TIF

Comments:

**THIS PAGE BLANK (USPTO)**